Thermal TG0361C 单组份导热凝胶

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Thermal TG0361C 是一种具有高导热，低压缩应力和优异可靠性的单组份导热凝胶。其具有良好的弥合公差能力，适用于自动化点胶以及丝网印刷等应用场景。该产品可在常温下短期储存，并在高温下固化形成具有弹性的垫片.

Thermal TG0361C is a kind of one-component thermal conductive gel with high thermal conductivity, low compression stress and excellent reliability performance. The material provides good gap filling ability and could be used for automatic dispensing and screen printing. This product can be stored at RT for short-term and cured at elevated temperature to form elastic pad.

Features 特性

- High Thermal Conductivity
  高导热
- Low Compression Stress 低应力
- High Reliability 高可靠性
- Automatic Dispensing
  自动化点胶

Applications 产品应用

- Consumer Electronics 消费电子
- Communication Equipment
  通讯设备
- Power Supply Controller
  电源控制系统
- Smart Wearable Product
  智能穿戴产品

Property 特性	Typical Value 典型值	Unit 单位	Test Method 测试方法
Composition 主要成分	Silicone Filled with Thermal Powder 硅胶&导热粉体		—
Color 颜色	Pink 粉色	—	Visual 目视
Thermal Conductivity 导热系数	3.6	W/m·K	ASTM D5470
Flow Rate 流速	200	g/min	30cc EFD, 90Psi
Viscosity 粘度@1s^{-1}	1000	Pa.s	ASTM D2196
Density 密度	3.25	g/cm^3	ASTM D792
Hardness 硬度（Shore 00）	40-60	—	ASTM D2240
Cure Time 固化时间	30-60@85°C	min	—
Temperature Range 耐温范围	-40 - 150	°C	—
Breakdown Voltage 击穿强度	6	KV/mm	ASTM D149
Flame Rating 阻燃等级	V-0	—	UL 94
RoHS Compliance 合规性	YES	—	—
Shelf Life 保存期	6	Month	≤-10°C,未启封
	7	Day	25±5°C, 50% RH，密封包装